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|  |                    |                     |           |
|--|--------------------|---------------------|-----------|
|  | Application Number | 10/813,407          |           |
|  | Filing Date        | March 29, 2004      |           |
|  | First Inventor     | Jiping Li           |           |
|  | Confirmation No.   | 5642                |           |
|  | Group Art Unit     | 2811                |           |
| Examiner Name  |                    | Unknown             |           |
| Total Number Of Pages In This Submission   | 8                  | Attorney Docket No. | BOX016 US |

**ENCLOSURES (check all that apply)**


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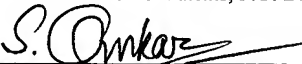
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| Firm or Individual Name | Omkar K. Suryadevara (Reg. No. 36,320)<br>Silicon Valley Patent Group LLP<br>2350 Mission College Boulevard, Suite 360<br>Santa Clara, California 95054 |
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Inventors: Jiping Li; Peter G. Borden; Edgar B. Genio  
Assignee: Applied Materials, Inc.  
Title: High Throughput Measurement Of Via Defects In Interconnects  
Serial No.: 10/813,407 Filing Date: March 29, 2004  
Examiner: Unknown Group Art Unit: 2811  
Docket No.: BOX016 US Confirmation No: 5642

Santa Clara, California  
March 23, 2005

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**INFORMATION DISCLOSURE STATEMENT  
UNDER 37 CFR §1.97(b)**

Dear Sir:

Pursuant to 37 C.F.R. § 1.56, §1.97 and §1.98, the Applicants submit for consideration in the above-identified patent application the documents listed on the accompanying Form PTO-1449. Copies of references numbered 47-96 are submitted herewith. The Examiner is requested to make these documents of record. The remaining references are not attached hereto, because these references are issued patents or publications which are readily available in the U.S. Patent and Trademark Office.

**In addition, Applicants submit for the Examiner's consideration, the prosecution histories of ten co-owned applications/patents, which are identified in the attached PTO-1449 as items 97-106.** The Applicants presume that the Examiner has access to and will review the cited applications/patents and the files thereof for any office actions, amendments or other materials that may be relevant to the patentability of the claims of the present application.

Citation of these prosecution histories (including the arguments against patentability advanced by Examiners in their respective Office Actions and the Applicants' arguments in

SILICON VALLEY  
PATENT GROUP LLP  
2350 Mission College Blvd.  
Suite 360  
Santa Clara, CA 95054  
(408) 982-8200  
FAX (408) 982-8210


the corresponding Amendments) is in accordance with the recent case DAYCO PRODUCTS, INC. v. TOTAL CONTAINMENT, INC., 02-1497, decided May 23, 2003 by the Court of Appeals for the Federal Circuit. The Examiner is presumed to be knowledgeable about the current case law, including the above-mentioned Dayco case. However, if the Examiner needs a copy of the Dayco case, please call the undersigned.

For any of the following U.S. patent application(s) cited in the attached PTO-1449 that are currently pending, the Applicants further presume that the Examiner will consider any **future** office actions, amendments or other materials in the file thereof that may be relevant to the patentability of the claims herein. **If the Applicants' understanding in this regard is not correct, please notify the undersigned so that copies of any such documents can be submitted to the Examiner.**


This Information Disclosure Statement is submitted pursuant to 37 CFR §1.97(b) as it is within three months of the filing date of a national application other than a continued prosecution application and/or before the mailing of a first Office Action on the merits. Accordingly, no fee is required.

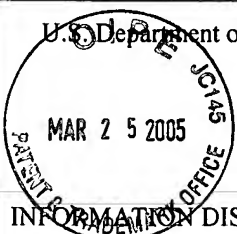
Applicants would appreciate the Examiner initialing and returning the Form PTO-1449, indicating that the information has been considered and made of record herein.

The information contained in this Information Disclosure Statement is to the best of my knowledge and is not to be construed as a representation that: (i) a complete search has been made; (ii) additional information material to the examination of this application does not exist; (iii) the information, protocols, results and the like reported by third parties are accurate or enabling; or (iv) the above information constitutes prior art to the subject invention.

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|    | <i>March 23, 2005</i> |
| Attorney for Applicant(s)   | Date of Signature     |

Respectfully submitted,

  
Omkar K. Suryadevara  
Attorney for Applicant(s)  
Reg. No. 36,320

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|--|--|-----------------------|----------------|
|  <p>U.S. Department of Commerce, Patent and Trademark Office</p> <p>INFORMATION DISCLOSURE STATEMENT BY APPLICANT</p> <p>(Use several sheets if necessary)</p> |  | Application No.:      | 10/813,407     |
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|  |  | Examiner Name:        | Unknown        |
|  |  | Confirmation No.:     | 5642           |
|  |  | Attorney Docket No.:  | BOX016 US      |

| U.S. Patent Documents |     |                    |          |                   |       |          |                               |
|-----------------------|-----|--------------------|----------|-------------------|-------|----------|-------------------------------|
| *Examiner<br>Initials |     | Document<br>Number | Date     | Name              | Class | Subclass | Filing Date if<br>Appropriate |
|                       | 1.  | 6,489,801          | 12/3/02  | Borden et al.     | 324   | 766      |                               |
|                       | 2.  | 6,812,047          | 11/2/04  | Borden et al.     | 438   | 16       |                               |
|                       | 3.  | 5,966,019          | 10/12/99 | Borden            | 324   | 752      |                               |
|                       | 4.  | 5,377,006          | 12/27/94 | Nakata            | 356   | 349      |                               |
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|                       | 6.  | 6,426,644          | 7/30/02  | Borden et al.     | 324   | 765      |                               |
|                       | 7.  | 5,042,951          | 8/27/91  | Gold et al.       | 356   | 369      |                               |
|                       | 8.  | 5,159,412          | 10/27/92 | Willenborg et al. | 356   | 445      |                               |
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|                       | 25. | 6,169,601          | 1/2/01   | Eremin et al.     | 356   | 240      |                               |

Examiner:

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|--|-----|--------------|----------|---------|-------|----------|-------------|----|
|  |     | Document     | Date     | Country | Class | Subclass | Yes         | No |
|  | 47. | 0 718 595    | 20.12.95 | EP      | G01B  | 6-Nov    |             |    |
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| 69. | A. Rosencwaig et al., "Thin-Film Thickness Measurements with Thermal Waves", Journal De Physique, October 1983, pp. C6-483 - C6-489  |
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| 98.  | US Appl. No. 10/722,724 entitled "Apparatus and Method For Measuring A Property of a Layer in a Multilayered Structure"                          |
| 99.  | US Appl. No. 10/090,316 entitled "Apparatus and Method For Measuring A Property Of A Layer In A Multilayered Structure"                          |
| 100. | US Appl. No. 09/521,232 entitled "Evaluating A Property Of A Multilayered Structure"   |
| 101. | US Appl. No. 10/977,380 entitled "Evaluating A Property Of A Multilayered Structure"   |
| 102. | US Appl. No. 09/788,273 entitled "Evaluating Sidewall Coverage In A Semiconductor Wafer"   |
| 103. | US Appl. No. 10/090,262 entitled "Evaluating A Multilayered Structure For Voids"   |
| 104. | US Appl. No. 10/984,463 entitled "Evaluating A Multilayered Structure For Voids"   |
| 105. | US Appl. No. 10/090,287 entitled "Identifying Defects In A Conductive Structure Of A Wafer, Based On Heat Transfer Therethrough"                 |
| 106. | US Appl. No. 10/979,397 entitled "Evaluation Of Openings In A Dielectric Layer"  |

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| Examiner:   | Date Considered: |
| * Examiner: Initial if reference is considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with your communication with applicant. |                  |